



DEFENSE LOGISTICS AGENCY
DEFENSE SUPPLY CENTER, COLUMBUS
POST OFFICE BOX 3990
COLUMBUS OH 43218-3990

IN REPLY
REFER TO

DSCC-VQ (VQE-04-7288/Mr. Werman/614-692-0631)

October 27, 2004

SUBJECT: Notification of Add-On Qualification, MIL-PRF-31032, CAGE Code: 04RV5

Mr. Brett Whitman
Lone Star Circuits
901 Hensley Drive
Wylie, TX 75098

Dear Mr. Whitman:

Qualification of your products is granted as a result of successful qualification testing to Military Performance Specification MIL-PRF-31032, Printed Circuit Board/Printed Wiring Board, and associated specification MIL-PRF-31032/1 and MIL-PRF-31032/2. This qualification is based on your technical review board (TRB) review and approval of the material and classification indicated below. Your add-on qualification expanded the following capabilities.

CAPABILITIES BY TECHNOLOGY / PRINTED BOARD TYPE:		
MIL-PRF-31032/1, /2	FROM:	TO:
Base Material	GF (Woven E-glass, Epoxy Resin)	GF (Woven E-glass, Epoxy Resin)
Max. Board Thickness	0.100"	0.119"
Number of Layers	12	18

CAPABILITIES BY TECHNOLOGY / PRINTED BOARD TYPE:		
MIL-PRF-31032/1, /2	FROM:	TO:
Base Material	GI (Woven E-glass, Polyimide Resin)	GI (Woven E-glass, Polyimide Resin)
Max. Board Thickness	0.070"	0.074"
Min. Drilled Hole Size	0.018"	0.012"
Aspect Ratio	3.89 : 1	6.2 : 1
Number of Layers	6	12
Min. Conductor Width	0.016"	0.005"
Min. Conductor Spacing	0.008"	0.005"
Controlled Impedance	N/A	62 / 37.5 ohm +/- 10%

This modified listing shall appear on the next issue of Qualified Manufacturers List QML-31032. The effective date of this qualification was when you completed testing of the product and is approved by DSCC on October 21, 2004.

MANUFACTURER NAME & ADDRESS Lone Star Circuits 901 Hensley Lane Wylie, TX 75098	BASIC PLANT LOCATION SAME	CAGE CODE: 04RV5 PHONE #: 972-771-1930 FAX #: 972-771-0360 EMAIL: sales@lonestar-circuits.com
CAPABILITIES BY TECHNOLOGY / PRINTED BOARD TYPE:		QUALIFICATION LETTERS:
MIL-PRF-31032 /1, /2 Max. Panel Size 18" X 24" Max. Board Thickness 0.119" Min. Drilled Hole Size 0.0100" Aspect Ratio 7.5 : 1 Number of Layers 18 Min. Conductor Width 0.004" Min. Conductor Spacing 0.005" Part Mounting MIX Base Materials GF (Woven E-Glass, Epoxy resin) Finish Systems Hot Air Solder Level (HASL) Hole Preparation Permanganate Desmear / Plasma Etchback Copper Plating Electrodeposited Acid Copper Solder Resist LPI, Dry Film		VQE-03-004341 VQE-04-005599 VQE-04-005891 VQE-05-007288
CAPABILITIES BY TECHNOLOGY / PRINTED BOARD TYPE:		QUALIFICATION LETTERS:
MIL-PRF-31032 /1, /2 Max. Panel Size 18" X 24" Max. Board Thickness 0.074" Min. Drilled Thru Hole Size 0.012" Aspect Ratio 6.2 : 1 Number of Layers 12 Min. Conductor Width 0.005" Min. Conductor Spacing 0.005" Part Mounting MIX Base Materials GI (Woven E-Glass, Polyimide resin) Finish Systems Hot Air Solder Level (HASL) Hole Preparation Plasma Etchback Copper Plating Electrodeposited Acid Copper Solder Resist Liquid Photoimageable (LPI) Controlled Impedance 62 / 37.5 ohm +/- 10%		VQE-04-004957 VQE-05-007288

1. A listing on the Qualified Manufacturers List (QML) does not guarantee acceptance of the product(s) in any future purchase.
2. QML listing does not constitute a waiver of any requirements of the specification or of the provisions of any contract.
3. Advertising of qualification information is permitted. Permission to use such information for advertising or publicity purposes is granted provided that such publicity or advertising does not state or imply that the product(s) is the only product of that type qualified or that the Department of Defense in any way recommends or endorses the manufacturer's product.
4. The listing applies only to products produced in the plant(s) specified in this letter of notification of qualification and applies to future amendments or revisions of the specification, unless otherwise notified.
5. The listing applies only to materials and manufacturing construction techniques identical to or covered by that (those) qualified. The qualifying activity must be advised in advance of any change to the materials and manufacturing construction techniques. Failure to notify the qualifying activity of any change to the materials and manufacturing construction techniques is cause for removal from the QML.

Because we are held responsible for the accuracy and currency of this QML, please let us know if your company discontinues production utilizing these materials or processes. If you have any questions, please contact Mr. Bill Werman at bill.werman@dla.mil or at (614) 692-0631.

Sincerely,

/SIGNED/

ROBERT P. EVANS
Chief
Sourcing and Qualification Unit